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(12) **United States Design Patent**
Chen

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- (54) **SEMI-ROUND SENSOR CAN**
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(CN)
 - (**) Term: **15 Years**
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 - (51) **LOC (14) Cl.** **09-09**
 - (52) **U.S. Cl.** **D34/9**
USPC **D34/9**
 - (58) **Field of Classification Search**
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CPC B65F 1/006; B65F 1/1638; B65F
2001/1653; B65F 2001/1661; B65F
2001/1669; B65F 2001/1676; B65F
2001/1684; B65F 2001/1692; B65F
1/1426
- See application file for complete search history.

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(Continued)

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(57) **CLAIM**

The ornamental design for a semi-round sensor can, as shown and described.

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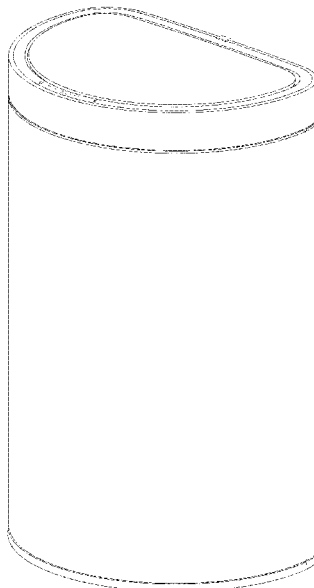
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DESCRIPTION

FIG. 1 is a perspective view of a semi-round sensor can, showing my new design.
FIG. 2 is a top plan view thereof.
FIG. 3 is a front elevation view thereof.
FIG. 4 is a right-side elevation view thereof.
FIG. 5 is a rear elevation view thereof.
FIG. 6 is a bottom plan view thereof; and,
FIG. 7 is a left-side elevation view thereof.
The broken lines in the drawings depict portions of the semi-round sensor can that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



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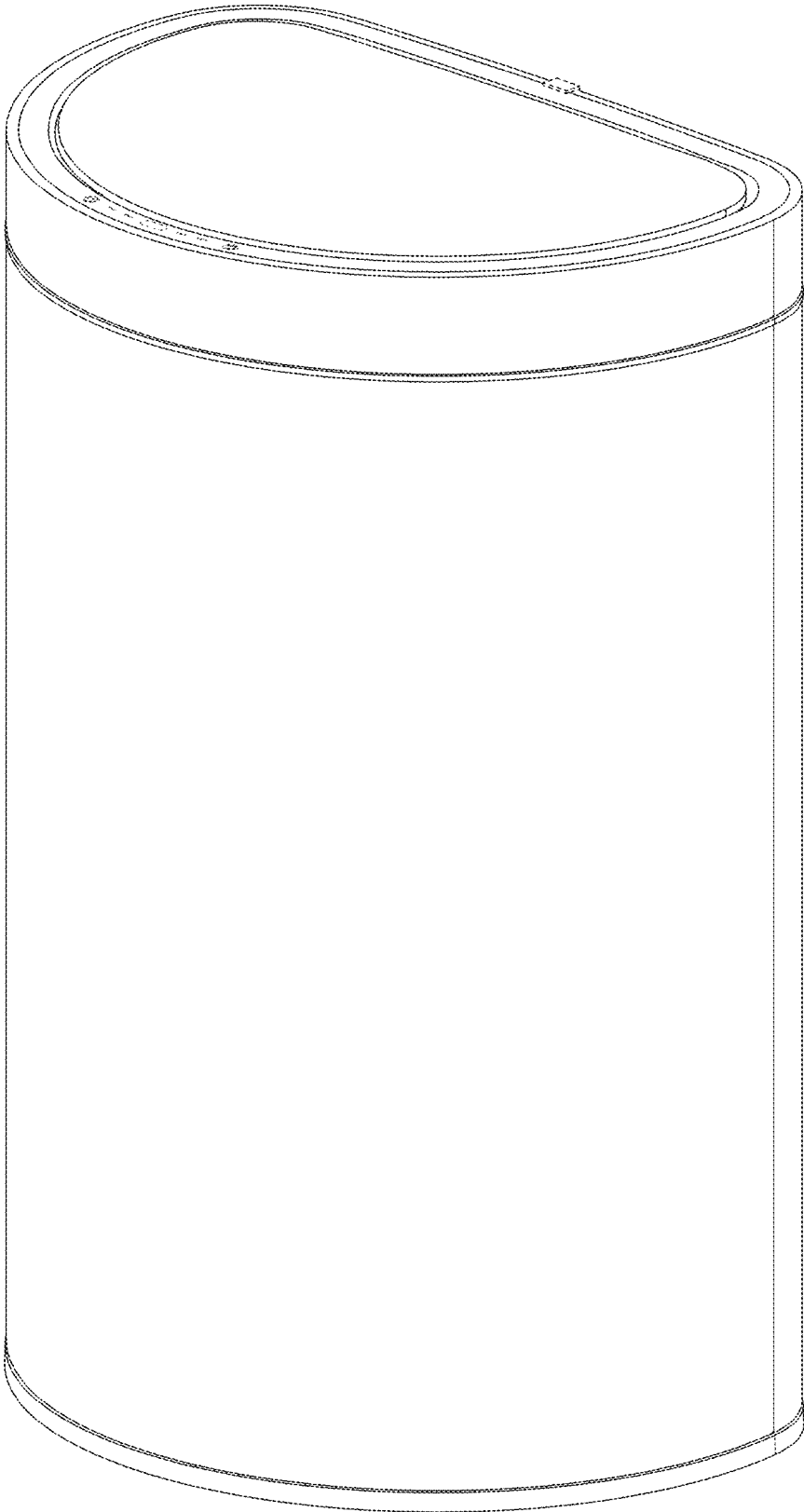


FIG. 1

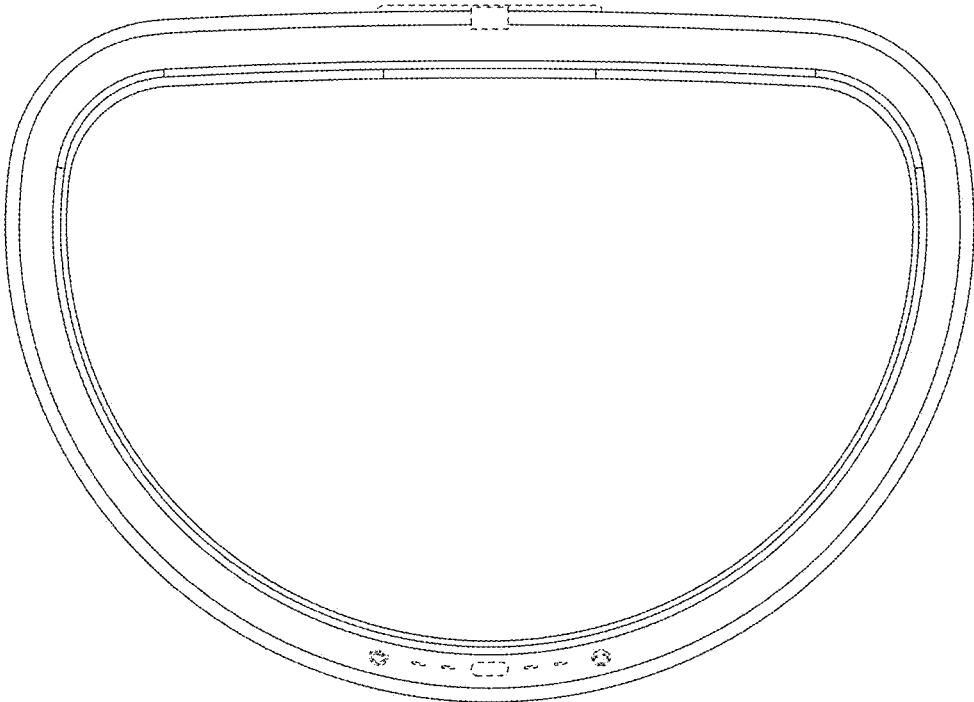


FIG. 2

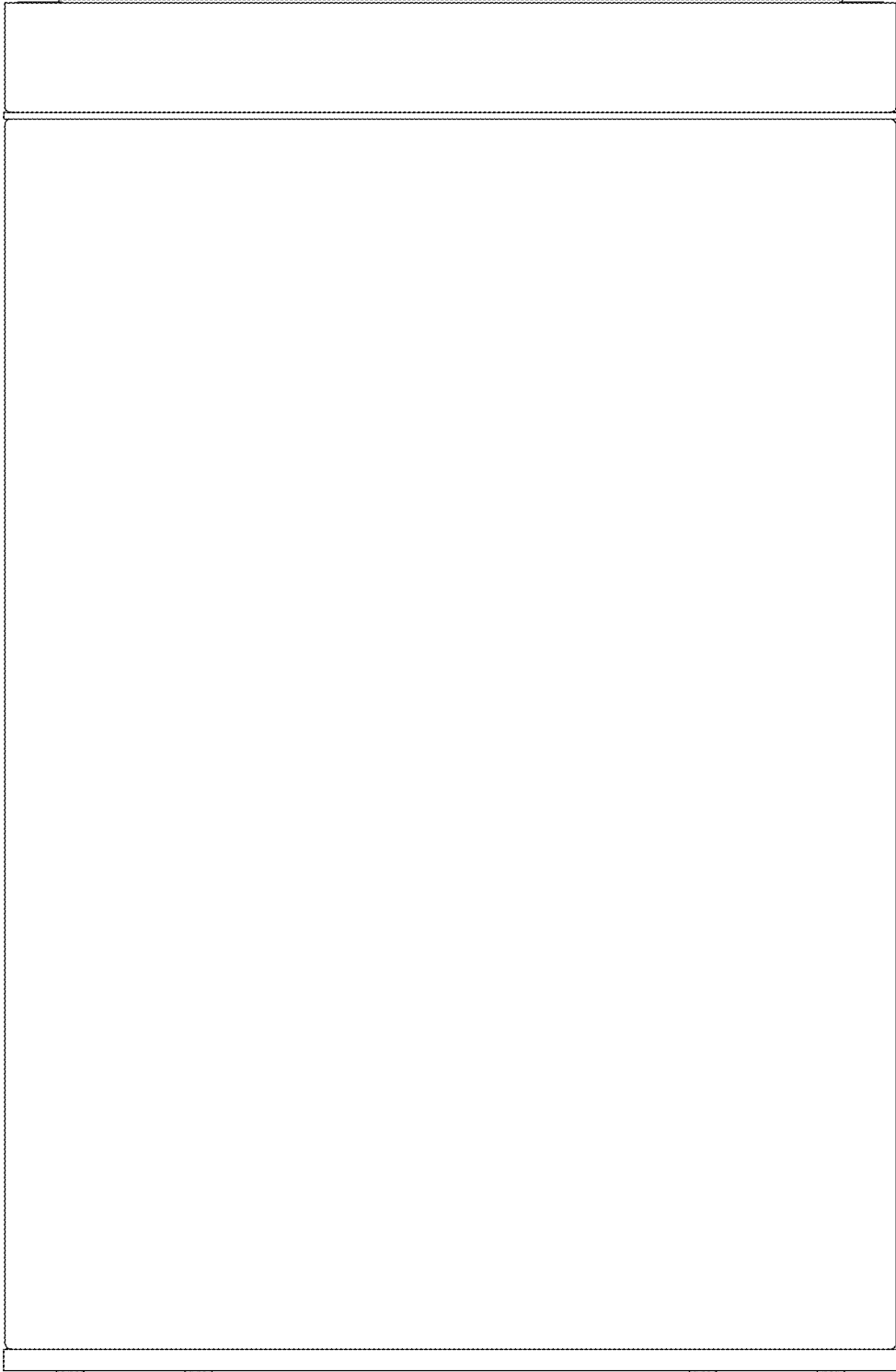


FIG. 3

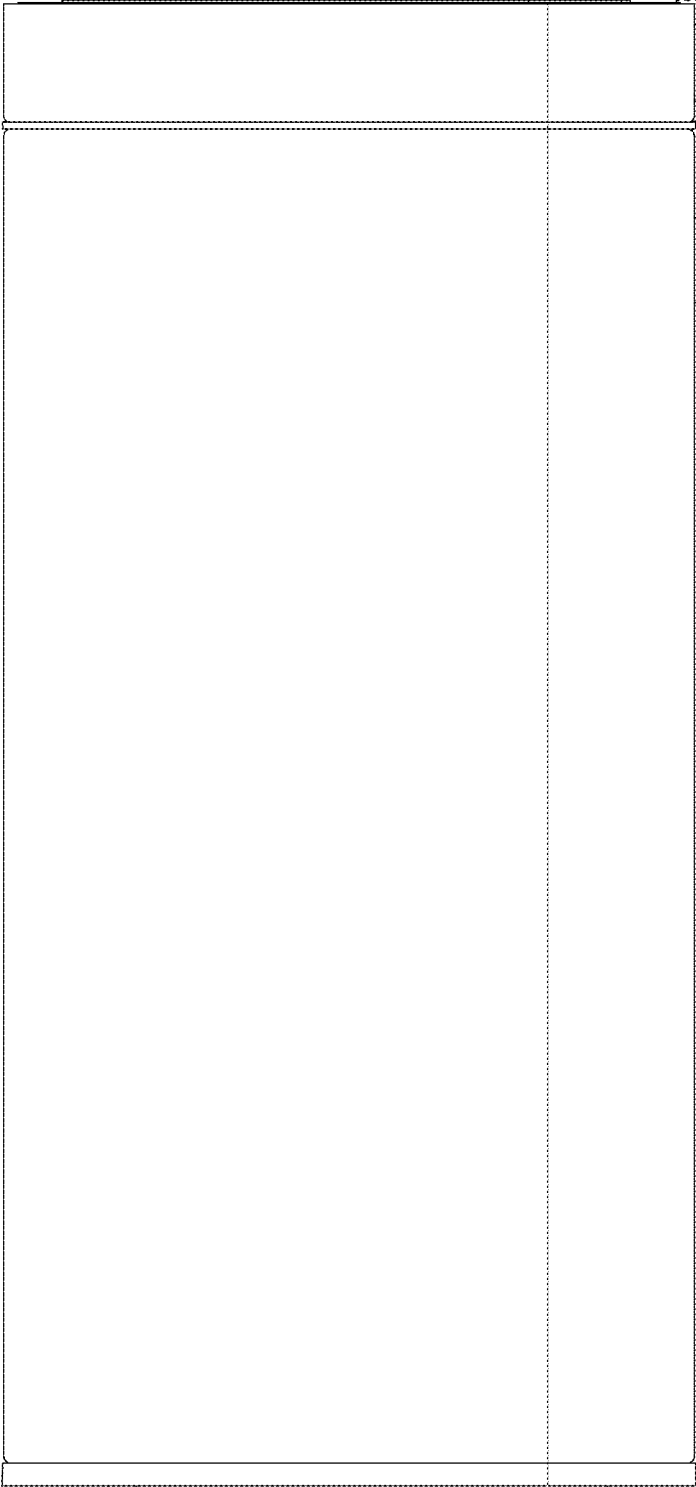


FIG. 4

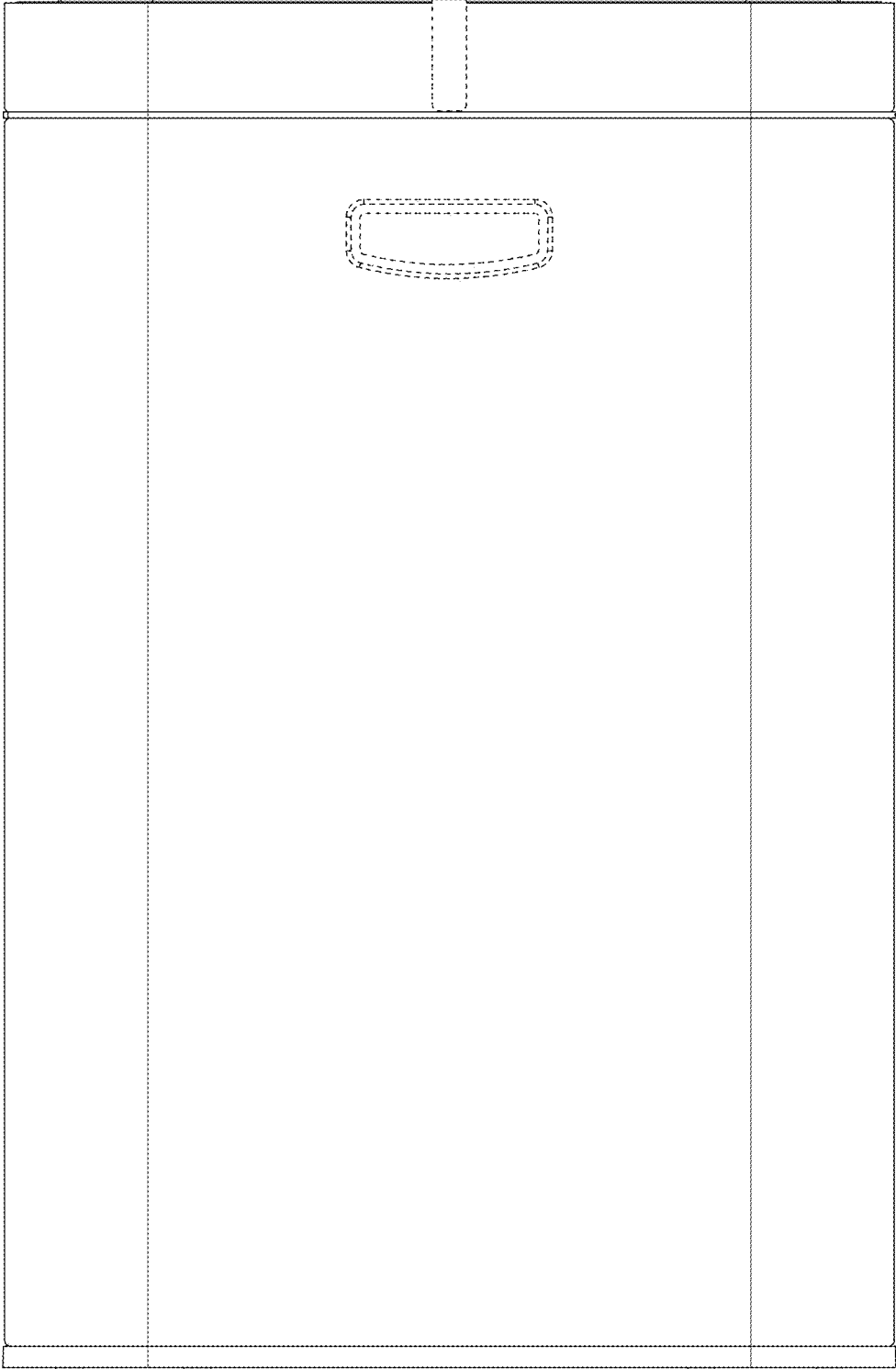


FIG. 5

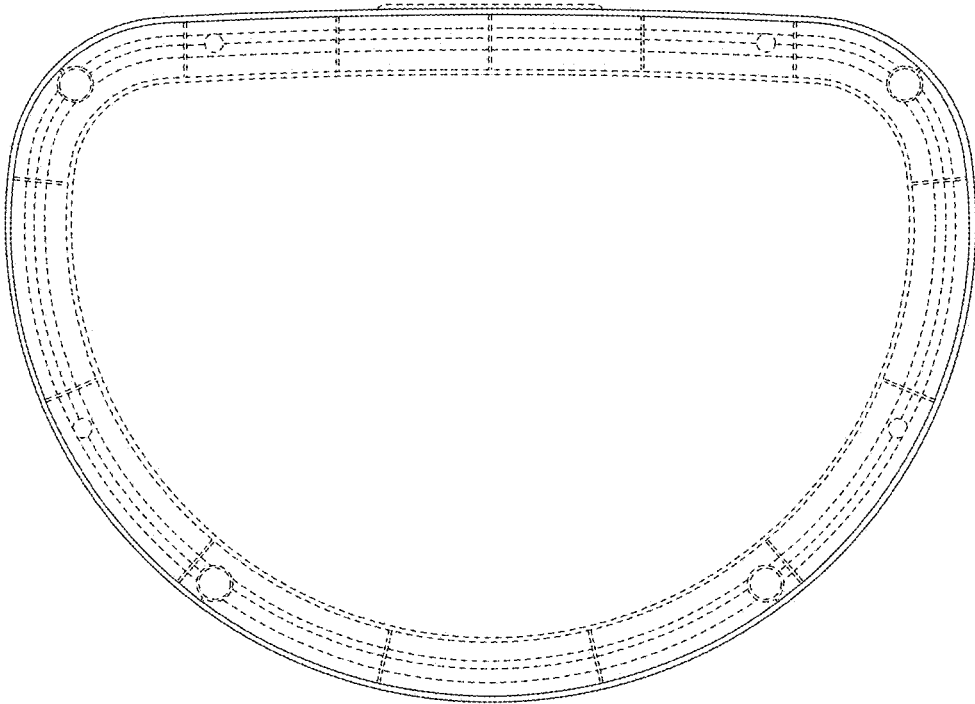


FIG. 6

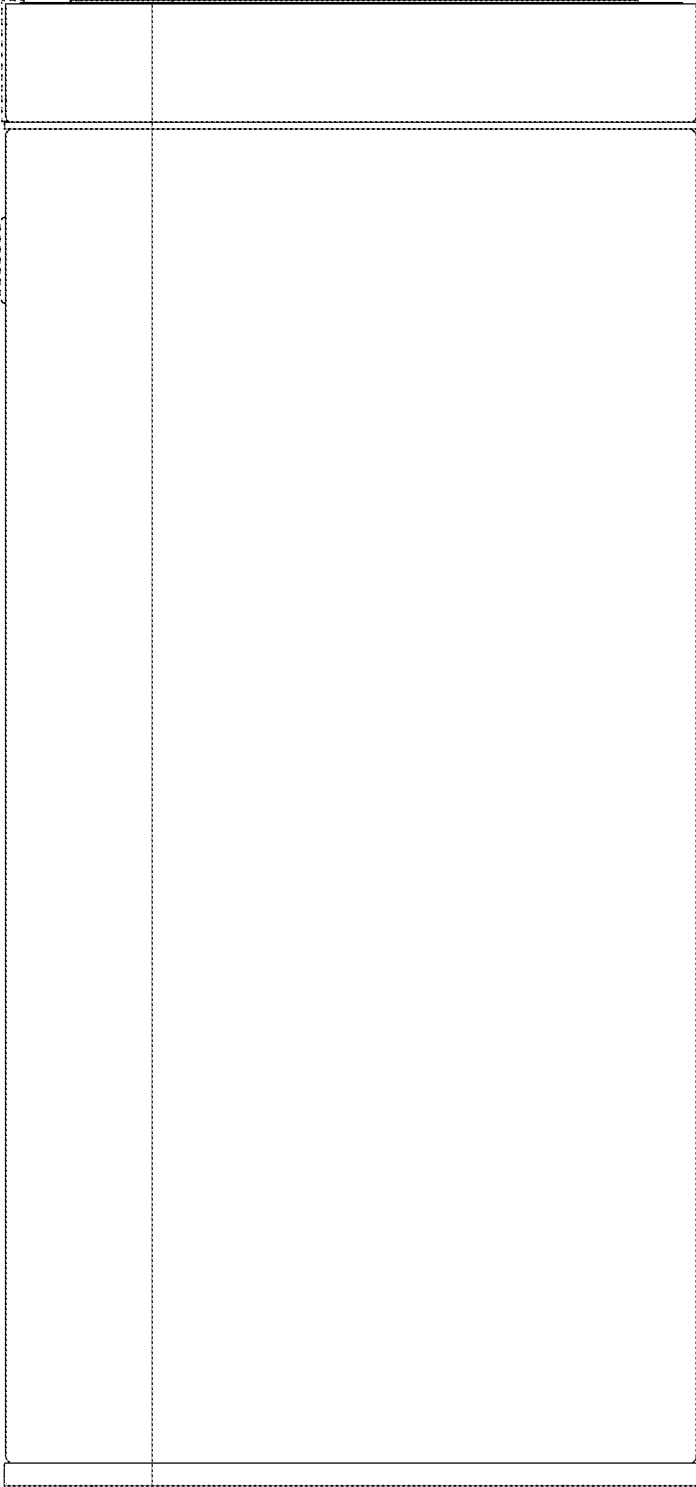


FIG. 7